

PI3DBS16412

3.3V, 1-20Gbps 2-Lane 2:1 Mux/De-Mux Switch

Features

- 4 Differential Channel, 2:1 Mux/DeMux
- Up to 20 Gbps for applications including USB3.0, USB3.1, 10GE, Thunderbolt 3, and SAS3.0
- Bi-directional operation
- 3dB bandwidth: 13 GHz
- Low Bit-to-Bit Skew, 3ps typ
- Low channel-to-channel skew, 10ps typ
- Low insertion loss: -1.3dB@5 GHz, -1.3dB@8 GHz, -2dB@10 GHz
- Return loss: -21dB@5 GHz, -13dB@8 GHz, -9dB@10 GHz
- Low power consumption - 300μA typ
- Supply Voltage 3.3V
- Industrial Temperature Range: -40°C to 85°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Packaging (Pb-free & Green):
 - 42-contact, TQFN (ZH42), 3.5x9mm
 - 40-contact, TQFN (ZLC40), 3x6mm

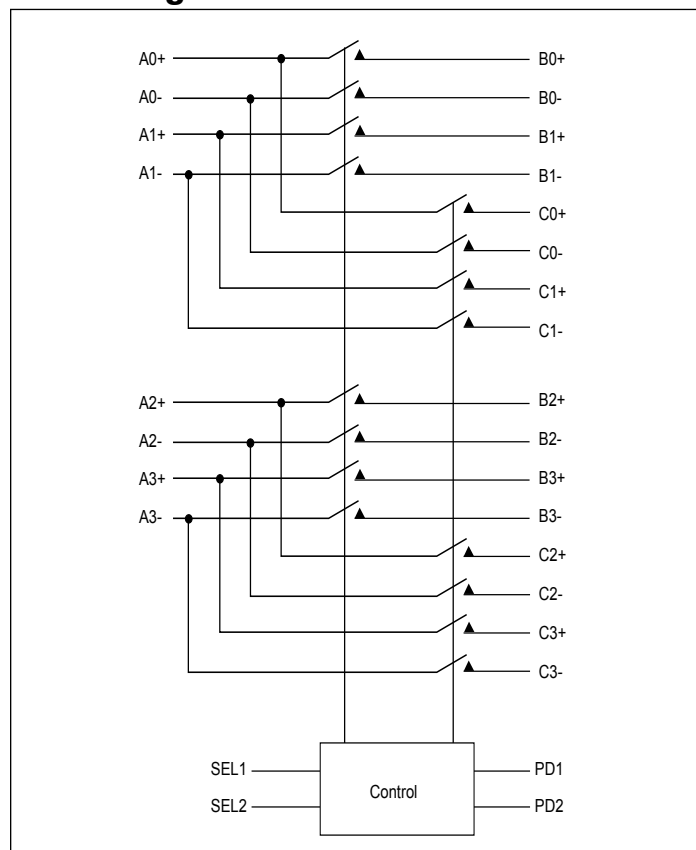
Description

The PI3DBS16412 is an 8 to 4 differential channel multiplexer/demultiplexer switch. This solution can switch multiple signal types up to data rate of 20Gbps. Using a unique design technique, Diodes has been able to minimize the impedance of the switch such that the attenuation observed through the switch is minimal. The unique design technique also offers a layout targeted for USB3.0, USB3.1, 10GE, Thunderbolt 3, and SAS3.0 signals, which minimizes the channel to channel skew as well as channel to channel crosstalk as required by high speed signals.

Application

- Routing high speed differential signals such as USB3.1 Gen 2, SAS3, PCIe4, TB3

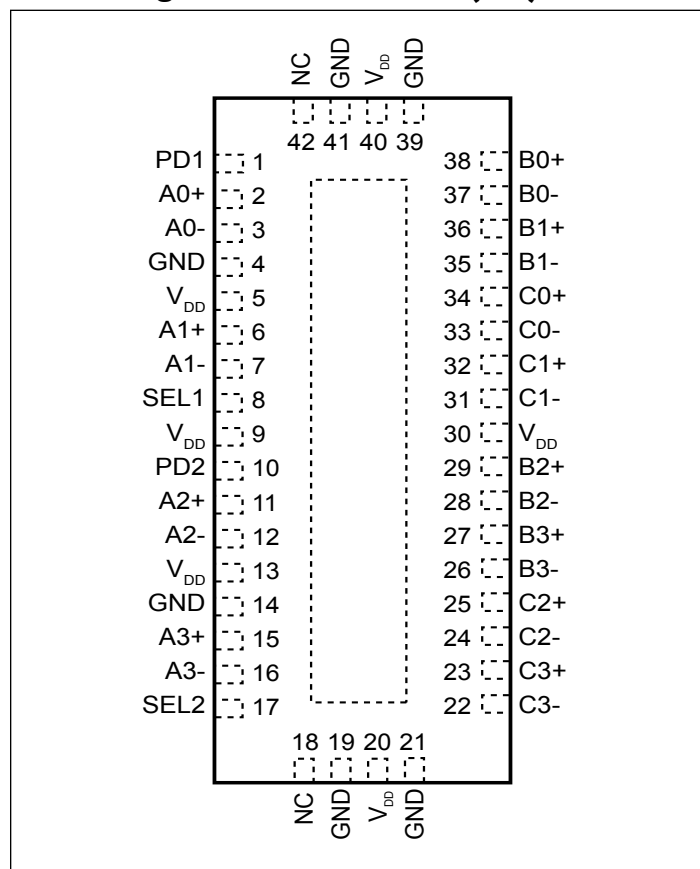
Block Diagram



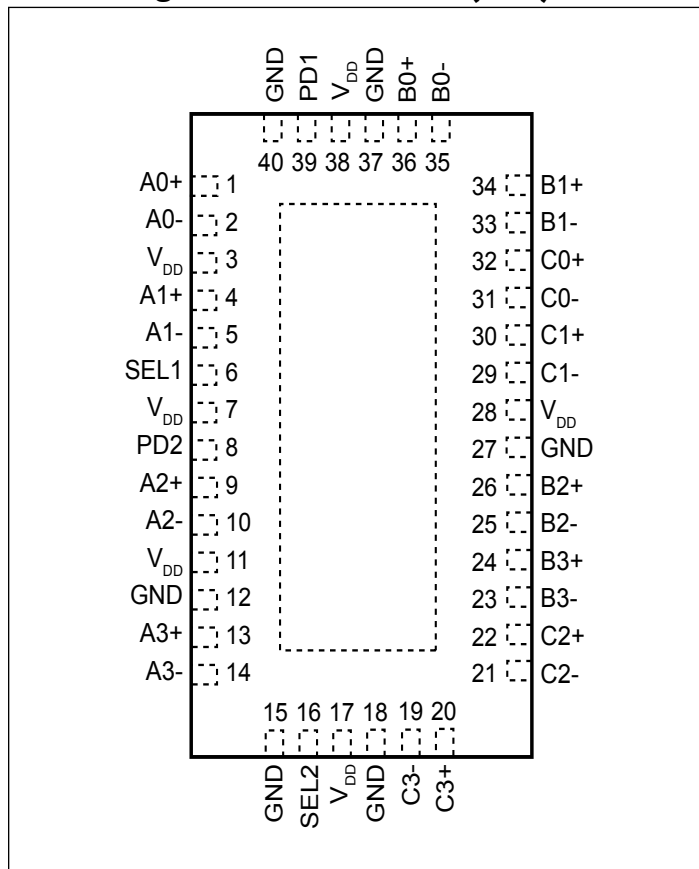
Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Configuration: 42-TQFN (ZH)



Pin Configuration: 40-TQFN (ZLC)



Truth Table

Function	SEL1	PD1
Power down & hi_z switches A0 & A1	x	1
A0 → B0 A1 → B1	0	0
A0 → C0 A1 → C1	1	0

Function	SEL2	PD2
Power down & hi_z switches A2 & A3	x	1
A2 → B2 A3 → B3	0	0
A2 → C2 A3 → C3	1	0

Pin Description

Pin #		Pin Name	I/O	Description
42-TQFN	40-TQFN			
2	1	A0+	I/O	Signal I/O, Channel 0, Port A, 100K pull-down
3	2	A0-		
6	4	A1+	I/O	Signal I/O, Channel 1, Port A, 100K pull-down
7	5	A1-		
11	9	A2+	I/O	Signal I/O, Channel 2, Port A, 100K pull-down
12	10	A2-		
15	13	A3+	I/O	Signal I/O, Channel 3, Port A, 100K pull-down
16	14	A3-		
38	36	B0+	I/O	Signal I/O, Channel 0, Port B
37	35	B0-		
36	34	B1+	I/O	Signal I/O, Channel 1, Port B
35	33	B1-		
29	26	B2+	I/O	Signal I/O, Channel 2, Port B
28	25	B2-		
27	24	B3+	I/O	Signal I/O, Channel 3, Port B
26	23	B3-		
34	32	C0+	I/O	Signal I/O, Channel 0, Port C
33	31	C0-		
32	30	C1+	I/O	Signal I/O, Channel 1, Port C
31	29	C1-		
25	22	C2+	I/O	Signal I/O, Channel 2, Port C
24	21	C2-		
23	20	C3+	I/O	Signal I/O, Channel 3, Port C
22	19	C3-		
8, 17	6, 16	SEL_X	I	Operation mode Select (when SEL=0: A→B, when SEL=1: A→C)
5, 9, 13, 20, 30, 40	3, 7, 11, 17, 28, 38	V _{DD}	Pwr	3.3V ±10% Positive Supply Voltage
4, 14, 19, 21, 39, 41, Center Pad	12, 15, 18, 27, 37, 40, Center Pad	GND	Pwr	Power ground
1, 10	39, 8	PD_X	I	Power Down Selet PD_X = 0, Device enable, PD_X = 1, Device disable channel stay hi_z
18, 42		NC		No Connect

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Supply Voltage to Ground Potential	-0.5V to +3.7V
Channel DC Input Voltage	-0.5V to 1.5V
DC Output Current	120mA
Power Dissipation	0.5W
Control Logic DC Input Voltage	-0.5V
Maximum Stress Voltage (MSV)	3.8V
ESD (HBM)	1KV

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{DD}	3.3V Power Supply		3.0	3.3	3.6	V
I _{DD}	Current consumption in normal operation	SEL = GND or V _{DD} , PD = Low		0.5	1.8	mA
I _{DDQ}	Current consumption when all switches are disabled	V _{DD} = 3.3V, PD = High		0.3		mA
P _{DD}	Total Power from VDD 3.3V supply	Control pins = GND or V _{DD}		2		mW
P _{DDQ}	Power consumption when all switches are disabled	V _{DD} = 3.3V, PD = High		1.1		mW
T _A	Operating temperature range		-40		85	°C

DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions ⁽¹⁾	Min.	Typ. ⁽¹⁾	Max.	Units
V _{IH} - cntrl signals	Input HIGH Voltage for SEL and PD	V _{DD} = 3.3V	1.4			V
V _{IL} - cntrl signals	Input LOW Voltage for SEL and PD	V _{DD} = 3.3V			0.4	
V _{IK}	Clamp Diode Voltage	V _{DD} = Max., I _{input} = -18mA		-0.7	-1.2	
I _{IH_ctrl}	Input HIGH Current for SEL and PD	V _{DD} = Max., V _{input} = 3.3V	-50		+50	μA
I _{IL_ctrl}	Input LOW Current for SEL and PD	V _{DD} = Max., V _{input} = 0V	-10		+10	
I _{OZH}	HighZ HIGH Current, switch I/O pins	V _{DD} = 3.3V, V _{input} = 1.0V	-10		+10	μA
I _{OZL}	HighZ LOW Current, switch I/O pins	V _{DD} = Max., V _{input} = 0V	-10		+10	μA
I _{IH}	Input HIGH Current for A _N	V _{DD} = Max., V _{input} = 1.2V	-20		+20	μA
	Input HIGH Current for B _N , C _N	V _{DD} = Max., V _{input} = 1.2V	-10		+10	μA
I _{IL}	Input LOW Current for A _N , B _N & C _N	V _{DD} = Max., V _{input} = 0V	-10		+10	μA
V _p	Max voltage pass through tolerance analog switches (See Test Circuit)	V _{DD} = 3.3V, I _{PASS} = 10mA		1		V
V _{IN}	Analog Signal to input of switch			1.1	1.2	V

Note:

1. Typical values are at V_{DD} = 3.3V, T_A = 25°C ambient and maximum loading.

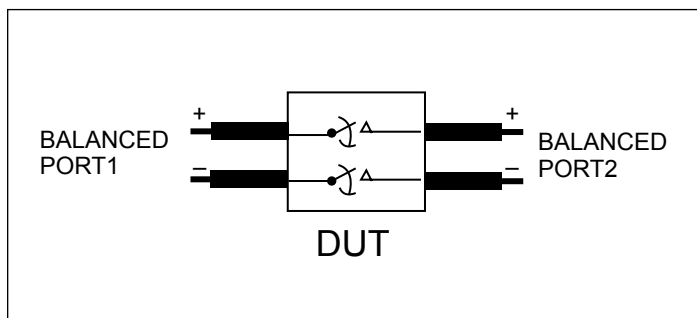
Dynamic Electrical Characteristics

Parameter	Description	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Units
DDIL	Differential Insertion Loss	f=2.5GHz f=4.0GHz f=5.0GHz f=8.0GHz f=10.0GHz		-0.8 -0.9 -1.2 -1.3 -2.0		dB
DDRL	Differential Return Loss	f= 2.5GHz f= 4.0GHz f= 5.0GHz f= 8.0GHz f=10.0GHz		-25.0 -24.0 -21.0 -13.0 -9.0		dB
DDOI	Differential OFF Isolation	f= 2.5GHz f= 4.0GHz f= 5.0GHz f= 8.0GHz f=10.0GHz		-27.0 -21.0 -19.0 -18.0 -19.0		dB
DDXT	Differential Crosstalk	f= 2.5GHz f= 4.0GHz f= 5.0GHz f=8.0GHz f=10.0GHz		-30.0 -29.0 -29.0 -30.0 -33.0		dB
BW	3dB Bandwidth			13		GHz

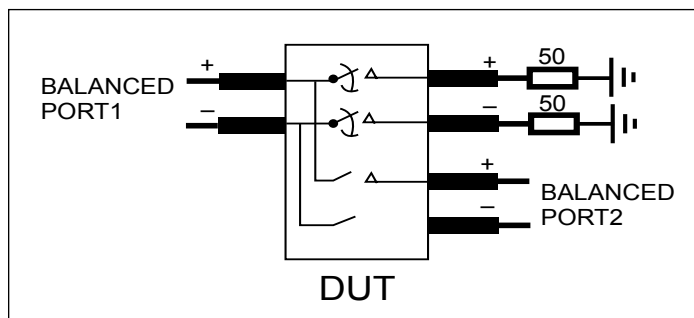
Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
tPZH, tPZL	Line Enable Time - SEL to A _N , B _N , C _N			200	350	ns
tPHZ, tPLZ	Line Disable Time - SEL to A _N , B _N , C _N			200	350	ns
tPLH	Propagation Delay, LOW to HIGH				50	ps
tPHL	Propagation Delay, HIGH to LOW				50	ps
t _{b-b}	Bit-to-bit skew within the same differential pair			3	10	ps
t _{ch-ch}	Channel-to-channel skew			10	20	ps

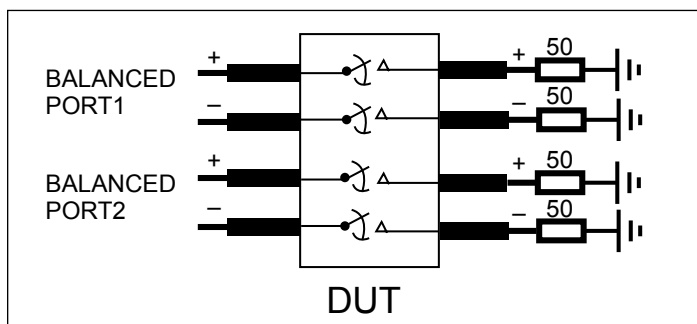
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Diff. Insertion Loss and Return Loss Test Circuit

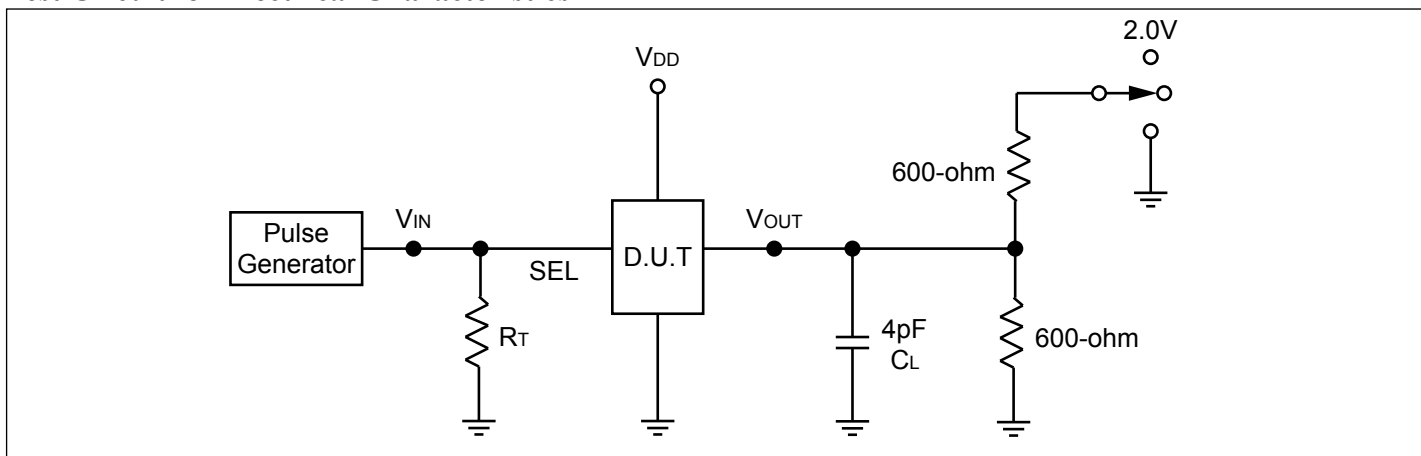


Diff. Off Isolation Test Circuit



Diff. Near End Xtalk Test Circuit

Test Circuit for Electrical Characteristics⁽¹⁻⁵⁾



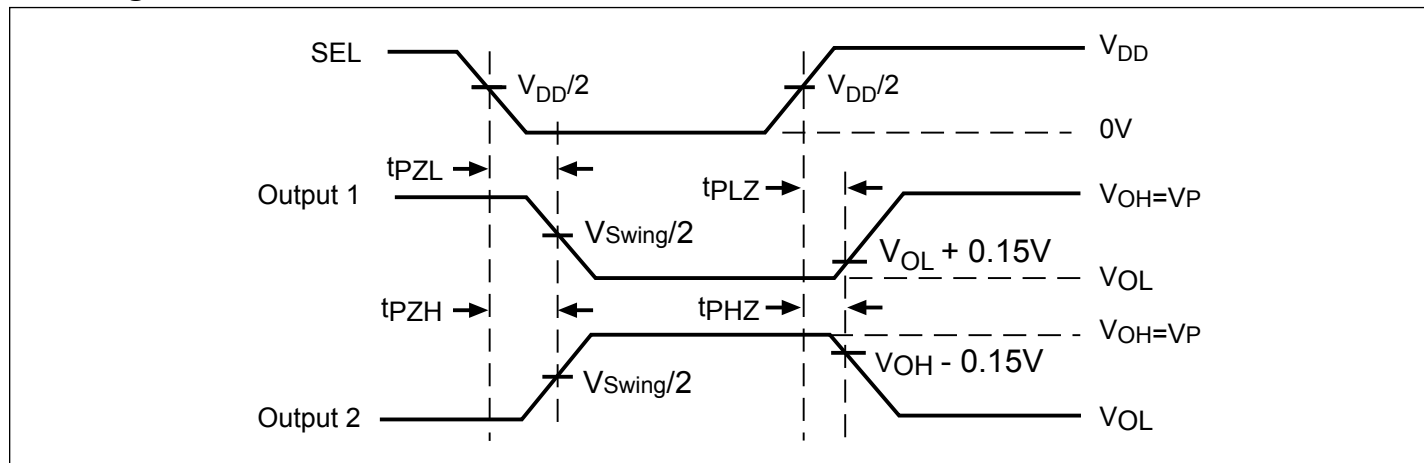
Notes:

1. CL = Load capacitance: includes jig and probe capacitance.
2. RT = Termination resistance: should be equal to ZOUT of the Pulse Generator
3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
4. All input impulses are supplied by generators having the following characteristics: PRR ≤ MHz, ZO = 50Ω, tR ≤ 2.5ns, tF ≤ 2.5ns.
5. The outputs are measured one at a time with one transition per measurement.

Switch Position

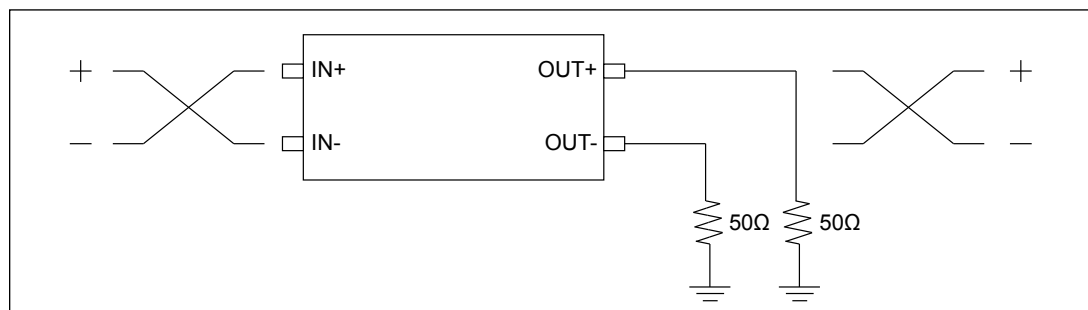
Test	Switch
t_{PLZ}, t_{PZL}	2.0V
t_{PHZ}, t_{PZH}	GND

Switching Waveforms



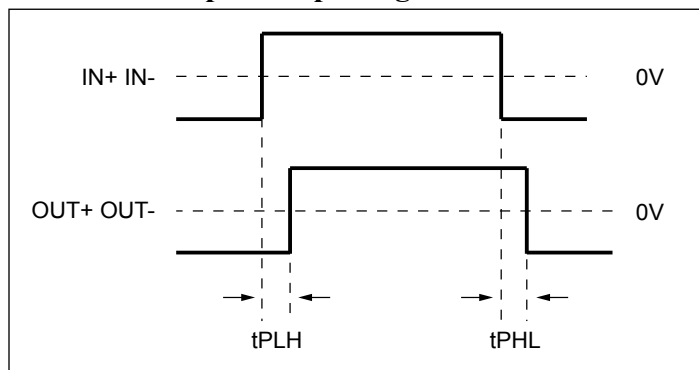
Voltage Waveforms Enable and Disable Times

Test Circuit for Propagation Delay

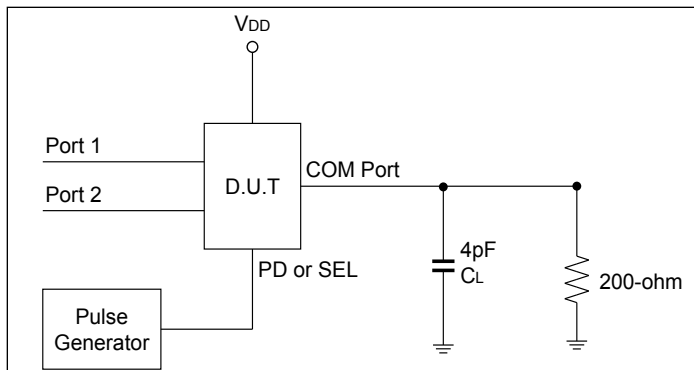


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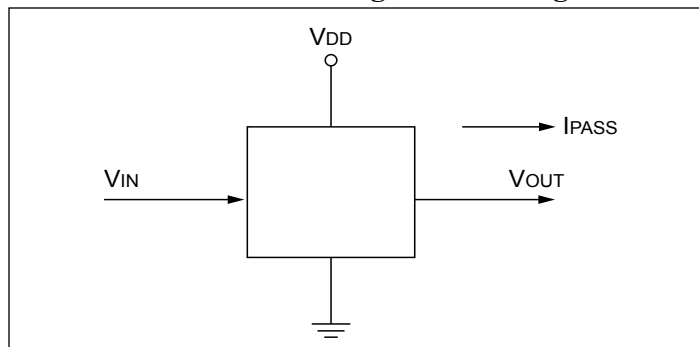
Differential Input/Output Signal Waveform



Test Circuit for SEL Switching Time

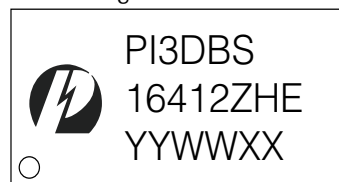


Test Circuit for Max Voltage Pass through



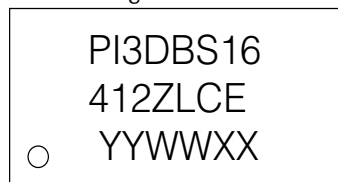
Part Marking

ZH Package



YY: Year
WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

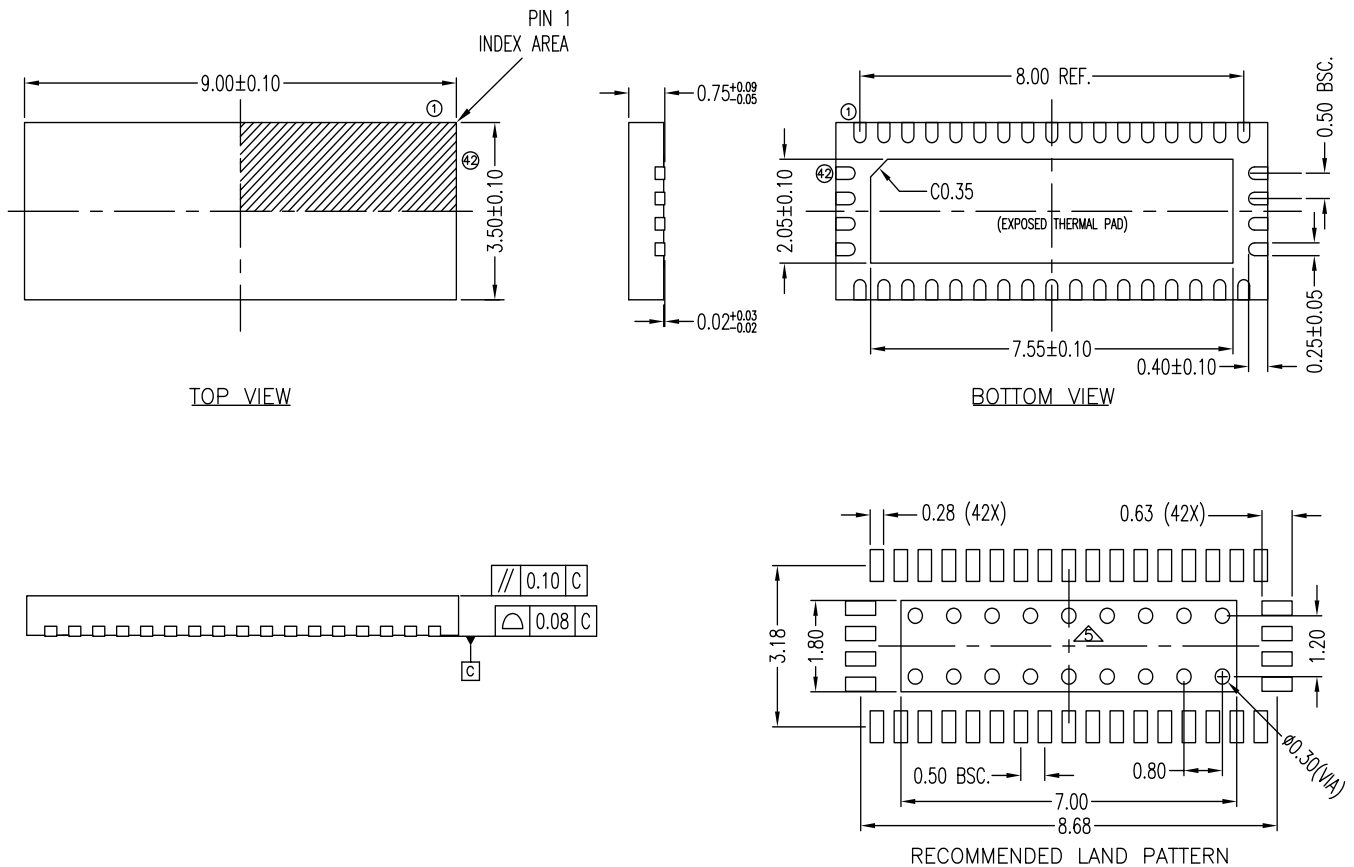
ZLC Package



YY: Year
WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

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Packaging Mechanical: 42-TQFN (ZH)



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL IS RECOMMENDED).

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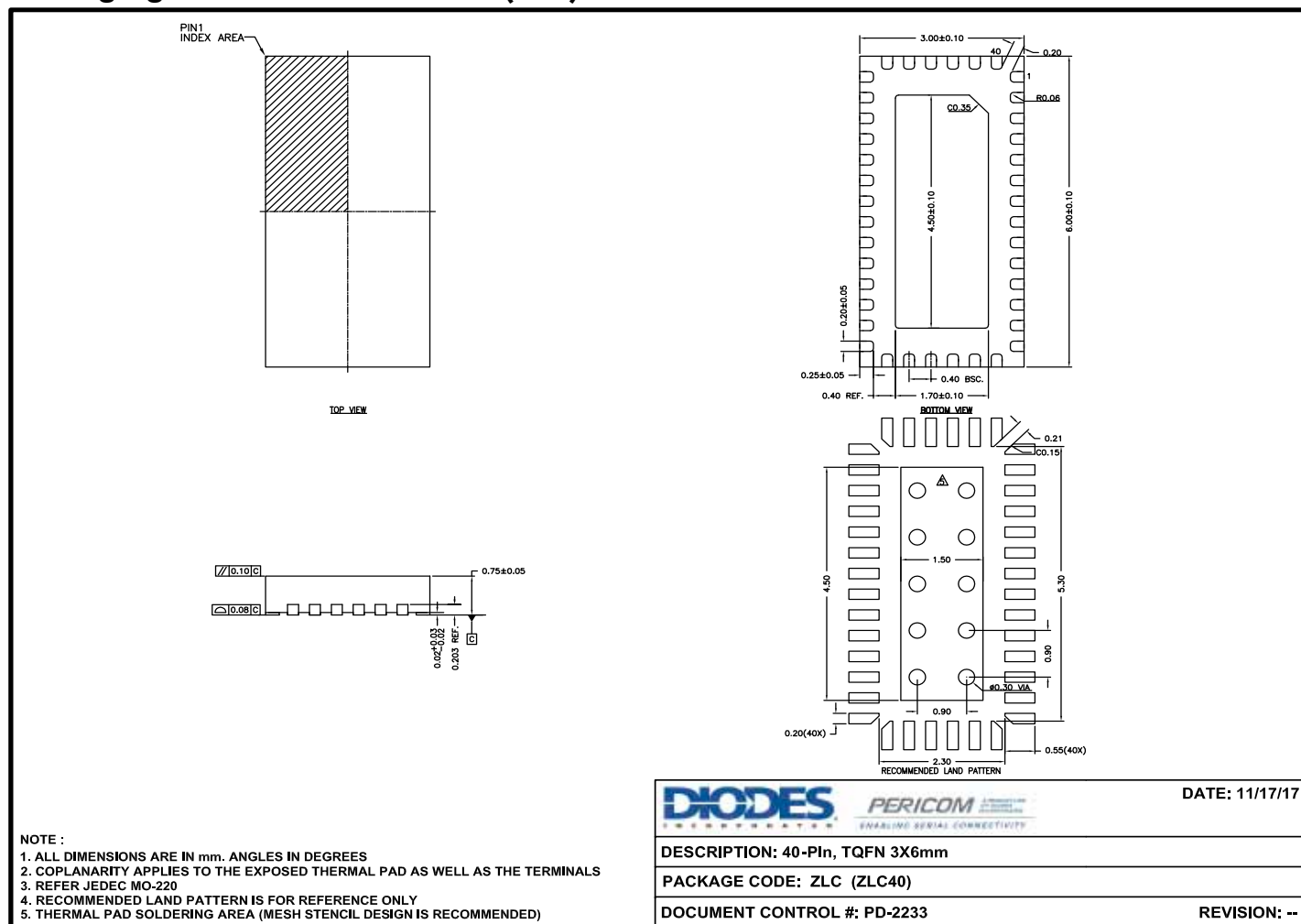
DATE: 04/25/17

DESCRIPTION: 42-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZH (ZH42)

DOCUMENT CONTROL #: PD-2035

REVISION: G

PI3DBS16412
Packaging Mechanical: 40-TQFN (ZLC)


For latest package info.

 please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>
Ordering Information

Ordering Number	Package Code	Package Description
PI3DBS16412ZHEX	ZH	42-Contact, Very Thin Quad Flat No-Lead (TQFN)
PI3DBS16412ZLC	ZLC	40-Pin, 3x6mm (TQFN)

Notes:

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4. E = Pb-free and Green
5. X suffix = Tape/Reel

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